Document Title

128Kx8 bit Low Power CMOS Static RAM

Revision History

Revision No.	History	Draft Data	Remark
0.0	Initial draft	July 15, 2002	Preliminary
0.1	Revised - Deleted 32-TSOP1-0820R Package Type. - Added Commercial product.	December 4, 2002	Preliminary
0.2	Revised - Added Lead Free 32-SOP-525 Product	May 13, 2003	Preliminary
0.3	Revised - Added Lead Free 32-TSOP1-0820F Product	June 21, 2003	Preliminary
1.0	Finalized - Changed I_{CC} from 10mA to 5mA - Changed $I_{CC}2$ from 35mA to 25mA - Changed I_{SB} from 3mA to 0.4mA - Changed I_{DR}(industrial) from 15μA to 10μA - Changed I_{DR}(Automotive) from 25μA to 20μA	September 16, 2003	Final
2.0	Revised - Changed I_{SB1} of Automotive product from 25μA to 30μA - Deleted 55ns Automotive product	July 15, 2004	Final
3.0	Revised - Changed I_{SB1} of Automotive product from 30μA to 50μA - Changed I_{DR} of Automotive product from 20μA to 25μA - Added Lead Free Products	March 27, 2005	Final

128Kx8 bit Low Power full CMOS Static RAM

FEATURES

- Process Technology: Full CMOS
- Organization: 128K x 8
- Power Supply Voltage: 4.5~5.5V
- Low Data Retention Voltage: 2V(Min)
- Three state output and TTL Compatible
- Package Type: 32-DIP-600, 32-SOP-525, 32-SOP-525, 32-TSOP1-0820F

GENERAL DESCRIPTION

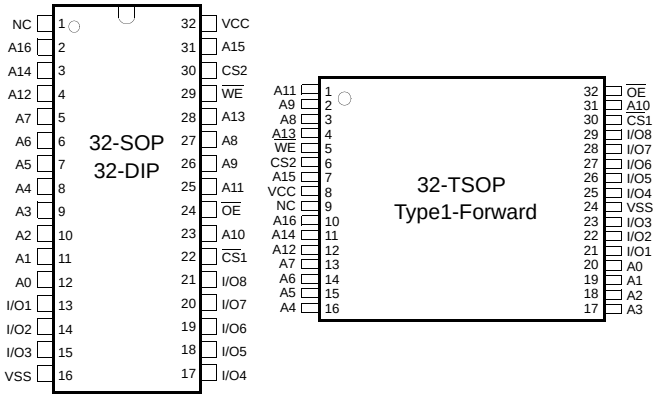
The K6X1008C2D families are fabricated by SAMSUNG′s advanced CMOS process technology. The families support verious operating temperature ranges and have various package types for user flexibility of system design. The families also support low data retention voltage for battery back-up operation with low data retention current.

PRODUCT FAMILY

Product Family	Operating Temperature	Vcc Range	Speed	Power Dissipation		PKG Type
				Standby (I_{SB1}, Max)	Operating (I_{CC2}, Max)	
K6X1008C2D-B	Commercial(0~70°C)	4.5~5.5V	55[1]/70ns	10μA	25mA	32-DIP-600, 32-SOP-525, 32-SOP-525 32-TSOP1-0820F
K6X1008C2D-F	Industrial(-40~85°C)			15μA		
K6X1008C2D-Q	Automotive(-40~125°C)		70ns	50μA		32-SOP-525, 32-TSOP1-0820F

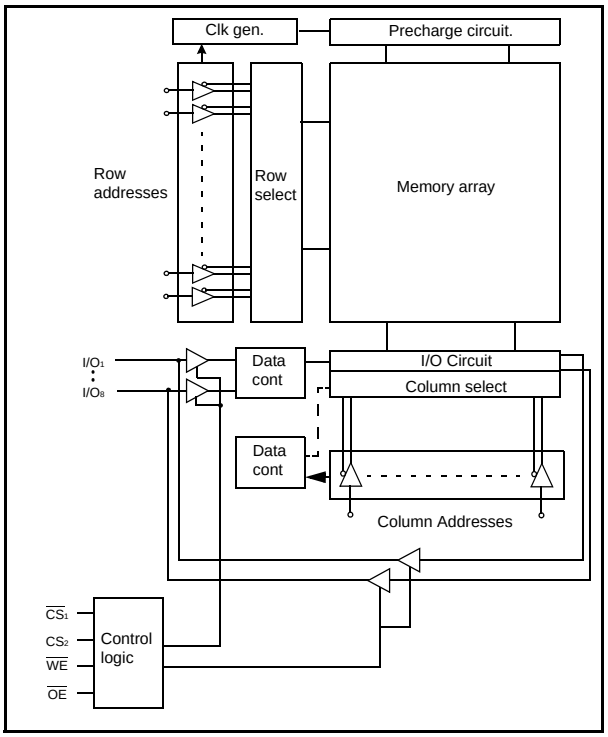
1. The parameters are tested with 50pF test load

PIN DESCRIPTION



Name	Function
$\overline{CS_1}$, CS_2	Chip Select Input
$\overline{OE}$	Output Enable Input
$\overline{WE}$	Write Enable Input
I/O_1~I/O_8	Data Inputs/Outputs
A_0~A_{16}	Address Inputs
Vcc	Power
Vss	Ground
NC	No Connection

FUNCTIONAL BLOCK DIAGRAM



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PRODUCT LIST

Commercial Products(0~70°C)		Industrial Products(-40~85°C)		Automotive Products(-40~125°C)	
Part Name	**Function**	**Part Name**	**Function**	**Part Name**	**Function**
K6X1008C2D-DB55	32-DIP, 55ns, LL	K6X1008C2D-DF55	32-DIP, 55ns, LL	K6X1008C2D-GQ70	32-SOP, 70ns, L
K6X1008C2D-DB70	32-DIP, 70ns, LL	K6X1008C2D-DF70	32-DIP, 70ns, LL	K6X1008C2D-BQ70[1)]	32-SOP, 70ns, L, LF
K6X1008C2D-GB55	32-SOP, 55ns, LL	K6X1008C2D-GF55	32-SOP, 55ns, LL	K6X1008C2D-TQ70	32-TSOP-F, 70ns, L
K6X1008C2D-GB70	32-SOP, 70ns, LL	K6X1008C2D-GF70	32-SOP, 70ns, LL	K6X1008C2D-PQ70[1)]	32-TSOP-F, 70ns, L, LF
K6X1008C2D-BB55[1)]	32-SOP, 55ns, LL, LF	K6X1008C2D-BF55[1)]	32-SOP, 55ns, LL		
K6X1008C2D-BB70[1)]	32-SOP, 70ns, LL, LF	K6X1008C2D-BF70[1)]	32-SOP, 70ns, LL		
K6X1008C2D-TB55	32-TSOP-F, 55ns, LL	K6X1008C2D-TF55	32-TSOP-F, 55ns, LL		
K6X1008C2D-TB70	32-TSOP-F, 70ns, LL	K6X1008C2D-TF70	32-TSOP-F, 70ns, LL		
K6X1008C2D-PB55[1)]	32-TSOP-F, 55ns, LL, LF	K6X1008C2D-PF55[1)]	32-TSOP-F, 55ns, LL		
K6X1008C2D-PB70[1)]	32-TSOP-F, 70ns, LL, LF	K6X1008C2D-PF70[1)]	32-TSOP-F, 70ns, LL		

1. Lead Free Product

FUNCTIONAL DESCRIPTION

$\overline{CS_1}$	CS_2	$\overline{OE}$	$\overline{WE}$	I/O	Mode	Power
H	X[1)]	X[1)]	X[1)]	High-Z	Deselected	Standby
X[1)]	L	X[1)]	X[1)]	High-Z	Deselected	Standby
L	H	H	H	High-Z	Output Disabled	Active
L	H	L	H	Dout	Read	Active
L	H	X[1)]	L	Din	Write	Active

1. X means don't care (Must be in high or low states)

ABSOLUTE MAXIMUM RATINGS[1)]

Item	Symbol	Ratings	Unit	Remark
Voltage on any pin relative to Vss	V_{IN},V_{OUT}	-0.5 to V_{CC}+0.5V(Max. 7.0V)	V	-
Voltage on Vcc supply relative to Vss	V_{CC}	-0.3 to 7.0	V	-
Power Dissipation	P_D	1.0	W	-
Storage temperature	T_{STG}	-65 to 150	°C	-
Operating Temperature	T_A	0 to 70	°C	K6X1008C2D-B
		-40 to 85	°C	K6X1008C2D-F
		-40 to 125	°C	K6X1008C2D-Q

1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation should be restricted to recommended operating condition. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS[1)]

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	Vcc	4.5	5.0	5.5	V
Ground	Vss	0	0	0	V
Input high voltage	V_{IH}	2.2	-	Vcc+0.5[2)]	V
Input low voltage	V_{IL}	-0.5[3)]	-	0.8	V

Note:
1. Commercial Product: T_A=0 to 70°C, Otherwise specified
   Industrial Product: T_A=-40 to 85°C, Otherwise specified
   Automotive Product: T_A=-40 to 125°C, Otherwise specified
2. Overshoot: Vcc+3.0V in case of pulse width≤30ns.
3. Undershoot: -3.0V in case of pulse width≤30ns.
4. Overshoot and undershoot are sampled, not 100% tested.

CAPACITANCE[1)] (f=1MHz, TA=25°C)

Item	Symbol	Test Condition	Min	Max	Unit
Input capacitance	C_{IN}	V_{IN}=0V	-	8	pF
Input/Output capacitance	C_{IO}	V_{IO}=0V	-	10	pF

1. Capacitance is sampled, not 100% tested

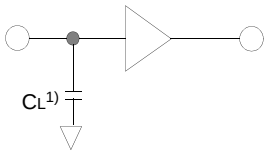
DC AND OPERATING CHARACTERISTICS

Item	Symbol	Test Conditions		Min	Typ	Max	Unit
Input leakage current	I_{LI}	V_{IN}=Vss to Vcc		-1	-	1	µA
Output leakage current	I_{LO}	$\overline{CS_1}$=V_{IH} or CS_2=V_{IL} or $\overline{OE}$=V_{IH} or $\overline{WE}$=V_{IL}, V_{IO}=Vss to Vcc		-1	-	1	µA
Operating power supply current	I_{CC}	I_{IO}=0mA, $\overline{CS_1}$=V_{IL}, CS_2=V_{IH}, V_{IN}=V_{IH} or V_{IL}, Read		-	-	5	mA
Average operating current	I_{CC1}	Cycle time=1µs, 100%duty, I_{IO}=0mA, $\overline{CS_1}$≤0.2V, CS_2≥Vcc-0.2V, V_{IN}≤0.2V or V_{IN}≥V_{CC}-0.2V		-	-	7	mA
	I_{CC2}	Cycle time=Min, 100% duty, I_{IO}=0mA, $\overline{CS_1}$=V_{IL}, CS_2=V_{IH}, V_{IN}=V_{IH} or V_{IL}		-	-	25	mA
Output low voltage	V_{OL}	I_{OL}=2.1mA		-	-	0.4	V
Output high voltage	V_{OH}	I_{OH}=-1.0mA		2.4	-	-	V
Standby Current(TTL)	I_{SB}	$\overline{CS_1}$=V_{IH}, CS2=V_{IL}, Other inputs=V_{IH} or V_{IL}		-	-	0.4	mA
Standby Current(CMOS)	I_{SB1}	$\overline{CS_1}$≥Vcc-0.2V, CS_2≥Vcc-0.2V or CS_2≤0.2V, Other inputs=0~Vcc	K6X1008C2D-B	-	-	10	µA
			K6X1008C2D-F	-	-	15	µA
			K6X1008C2D-Q	-	-	50	µA

AC OPERATING CONDITIONS

TEST CONDITIONS(Test Load and Input/Output Reference)

Input pulse level: 0.8 to 2.4V
Input rising and falling time: 5ns
Input and output reference voltage:1.5V
Output load(see right): C_L=100pF+1TTL
C_L=50pF+1TTL



1. Including scope and jig capacitance

AC CHARACTERISTICS

(V_{CC}=4.5~5.5V, Commercial product: T_A=0 to 70°C, Industrial product: T_A=-40 to 85°C, Automotive product: T_A=-40~125°C)

Parameter List		Symbol	Speed Bins				Units
			55ns[1]		70ns		
			Min	Max	Min	Max	
Read	Read Cycle Time	t_{RC}	55	-	70	-	ns
	Address Access Time	t_{AA}	-	55	-	70	ns
	Chip Select to Output	t_{CO}	-	55	-	70	ns
	Output Enable to Valid Output	t_{OE}	-	25	-	35	ns
	Chip Select to Low-Z Output	t_{LZ}	10	-	10	-	ns
	Output Enable to Low-Z Output	t_{OLZ}	5	-	5	-	ns
	Chip Disable to High-Z Output	t_{HZ}	0	20	0	25	ns
	Output Disable to High-Z Output	t_{OHZ}	0	20	0	25	ns
	Output Hold from Address Change	t_{OH}	10	-	10	-	ns
Write	Write Cycle Time	t_{WC}	55	-	70	-	ns
	Chip Select to End of Write	t_{CW}	45	-	60	-	ns
	Address Set-up Time	t_{AS}	0	-	0	-	ns
	Address Valid to End of Write	t_{AW}	45	-	60	-	ns
	Write Pulse Width	t_{WP}	40	-	50	-	ns
	Write Recovery Time	t_{WR}	0	-	0	-	ns
	Write to Output High-Z	t_{WHZ}	0	20	0	25	ns
	Data to Write Time Overlap	t_{DW}	20	-	25	-	ns
	Data Hold from Write Time	t_{DH}	0	-	0	-	ns
	End Write to Output Low-Z	t_{OW}	5	-	5	-	ns

1. The parameter is tested with 50pF test load. Commercial & Industrial Products only.

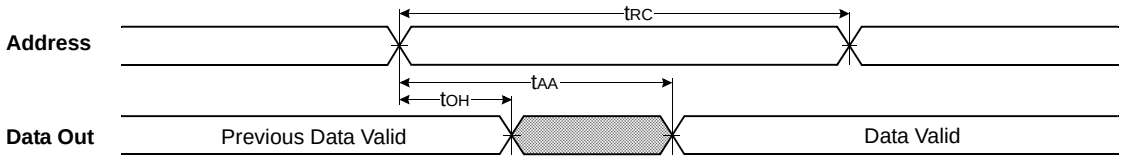
DATA RETENTION CHARACTERISTICS

Item	Symbol	Test Condition		Min	Typ	Max	Unit
Vcc for data retention	V_{DR}	$\overline{CS_1}$≥Vcc-0.2V[1]		2.0	-	5.5	V
Data retention current	I_{DR}	Vcc=3.0V, $\overline{CS_1}$≥Vcc-0.2V[1]	K6X1008C2D-B	-	-	10	µA
			K6X1008C2D-F	-	-	10	µA
			K6X1008C2D-Q	-	-	25	µA
Data retention set-up time	t_{SDR}	See data retention waveform		0	-	-	ms
Recovery time	t_{RDR}			5	-	-	

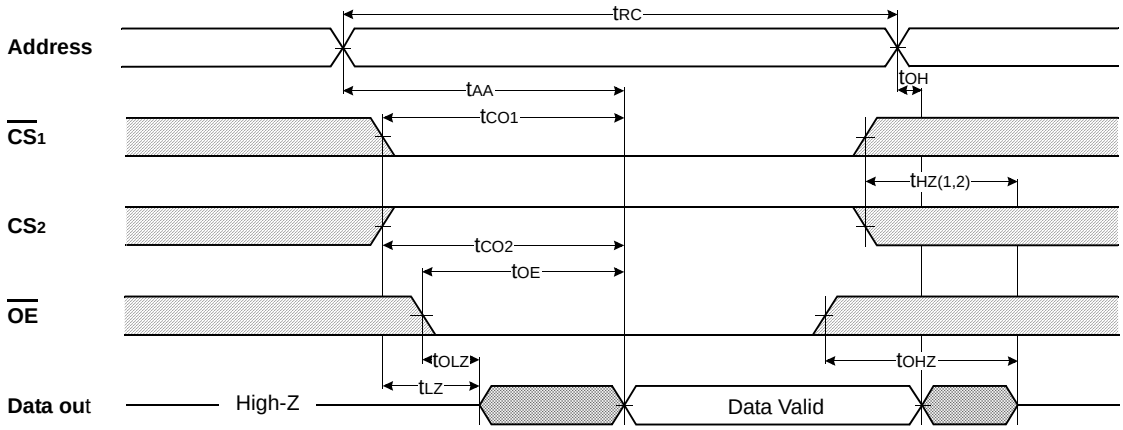
1. $\overline{CS_1}$≥Vcc-0.2V, CS_2≥Vcc-0.2V, or CS_2≤0.2V

TIMING DIAGRAMS

TIMING WAVEFORM OF READ CYCLE(1) (Address Controlled, $\overline{CS1}$=$\overline{OE}$=V_{IL}, CS2=$\overline{WE}$=V_{IH})



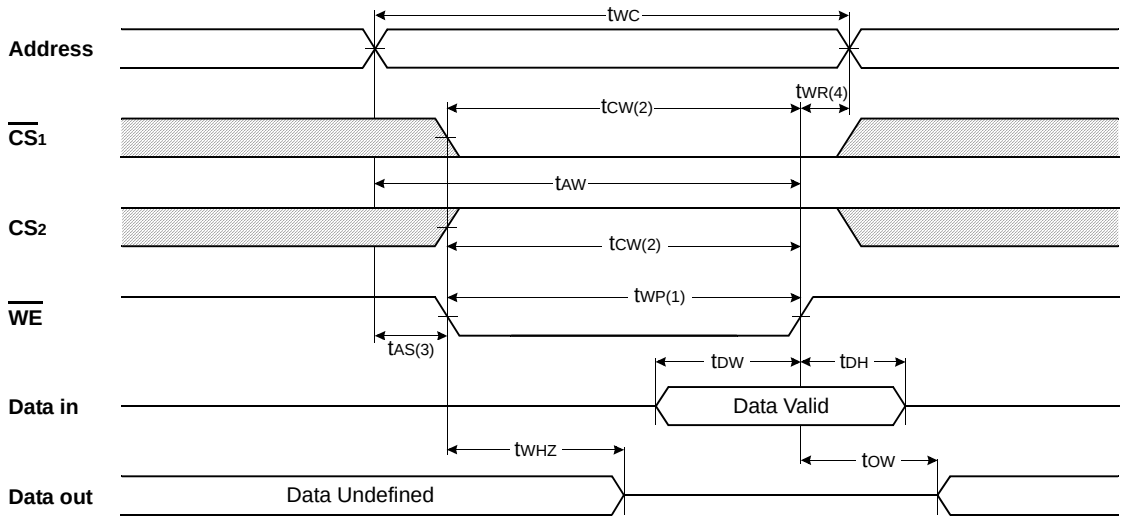
TIMING WAVEFORM OF READ CYCLE(2) ($\overline{WE}$=V_{IH})



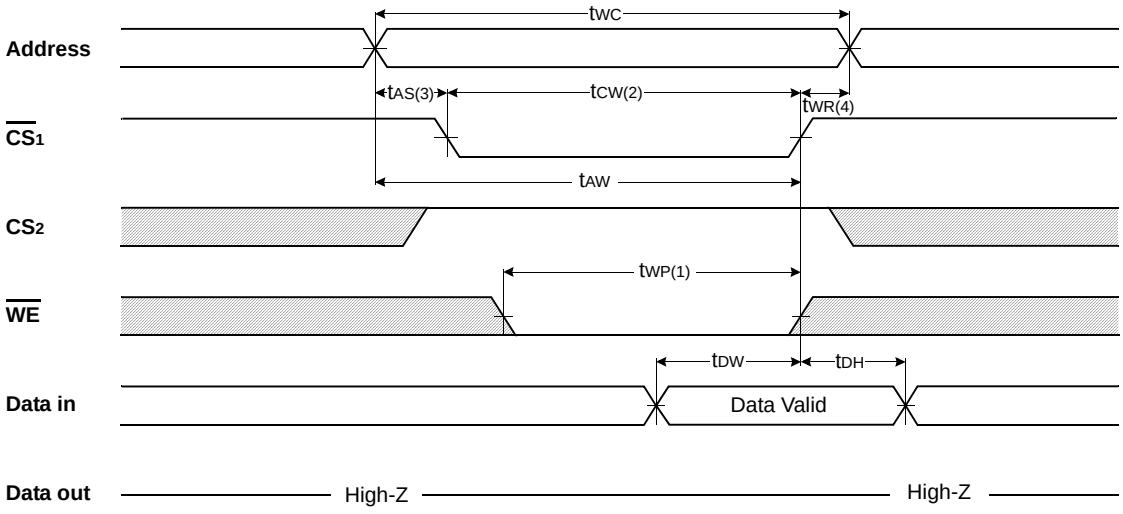
NOTES (READ CYCLE)

1. t_{HZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
2. At any given temperature and voltage condition, t_{HZ}(Max.) is less than t_{LZ}(Min.) both for a given device and from device to device interconnection.

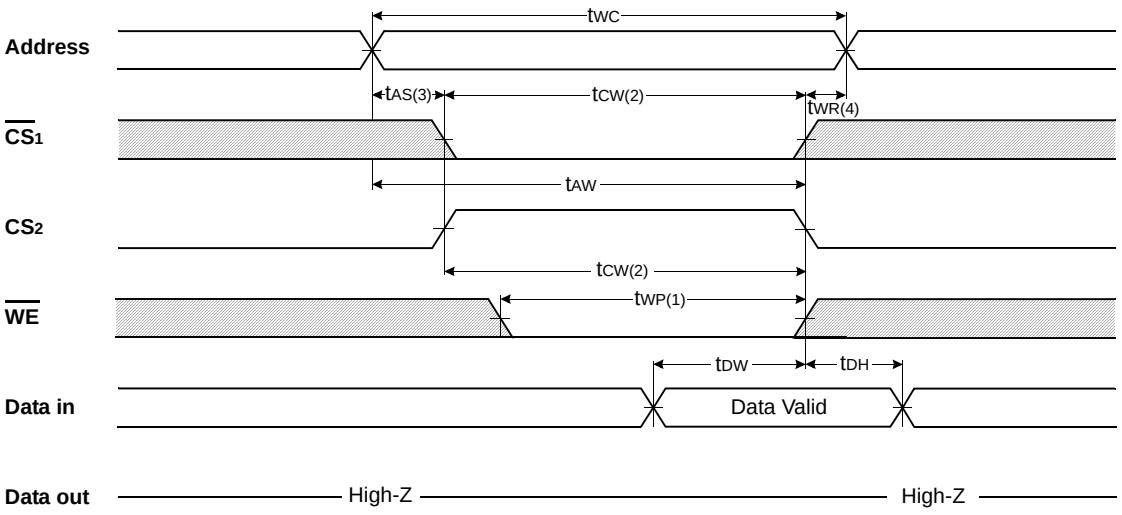
TIMING WAVEFORM OF WRITE CYCLE(1) ($\overline{WE}$ Controlled)



TIMING WAVEFORM OF WRITE CYCLE(2) ($\overline{CS_1}$ Controlled)



TIMING WAVEFORM OF WRITE CYCLE(3) (CS_2 Controlled)

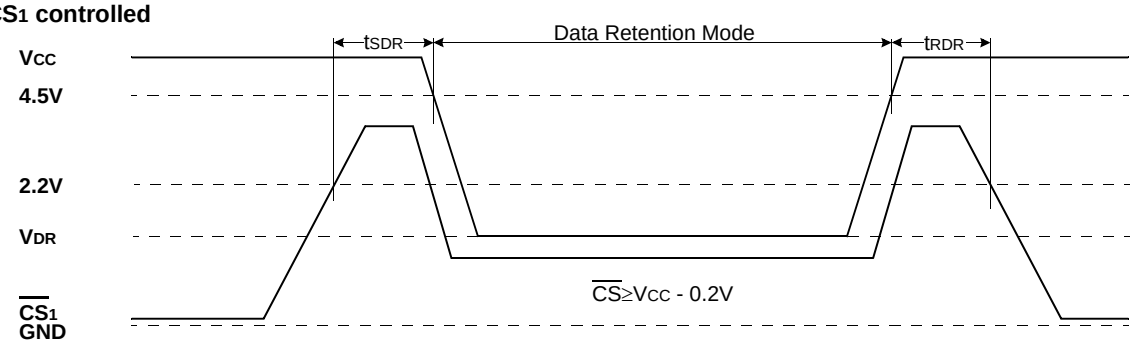


NOTES (WRITE CYCLE)

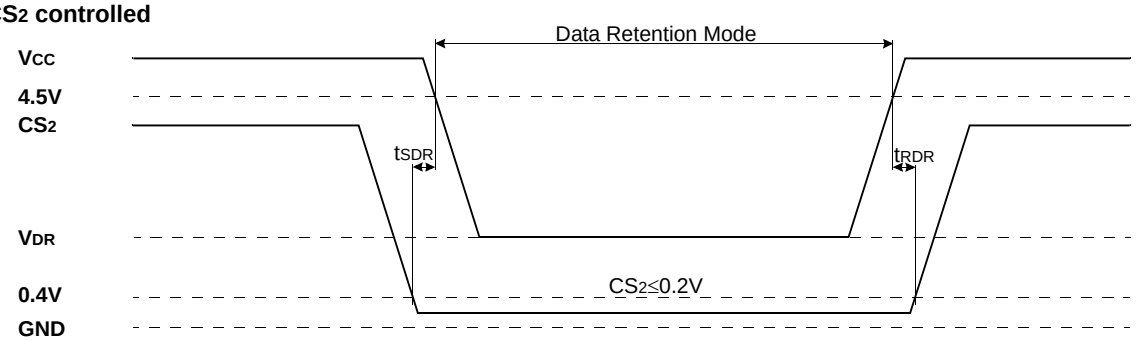
1. A write occurs during the overlap of a low $\overline{CS_1}$, a high CS_2 and a low $\overline{WE}$. A write begins at the latest transition among $\overline{CS_1}$ goes low, CS_2 going high and $\overline{WE}$ going low: A write end at the earliest transition among $\overline{CS_1}$ going high, CS_2 going low and $\overline{WE}$ going high, t_{WP} is measured from the begining of write to the end of write.
2. t_{CW} is measured from the $\overline{CS_1}$ going low or CS_2 going high to the end of write.
3. t_{AS} is measured from the address valid to the beginning of write.
4. t_{WR} is measured from the end of write to the address change. t_{WR} applied in case a write ends as $\overline{CS_1}$ or $\overline{WE}$ going high t_{WR2} applied in case a write ends as CS_2 going to low.

DATA RETENTION WAVE FORM

$\overline{CS_1}$ controlled



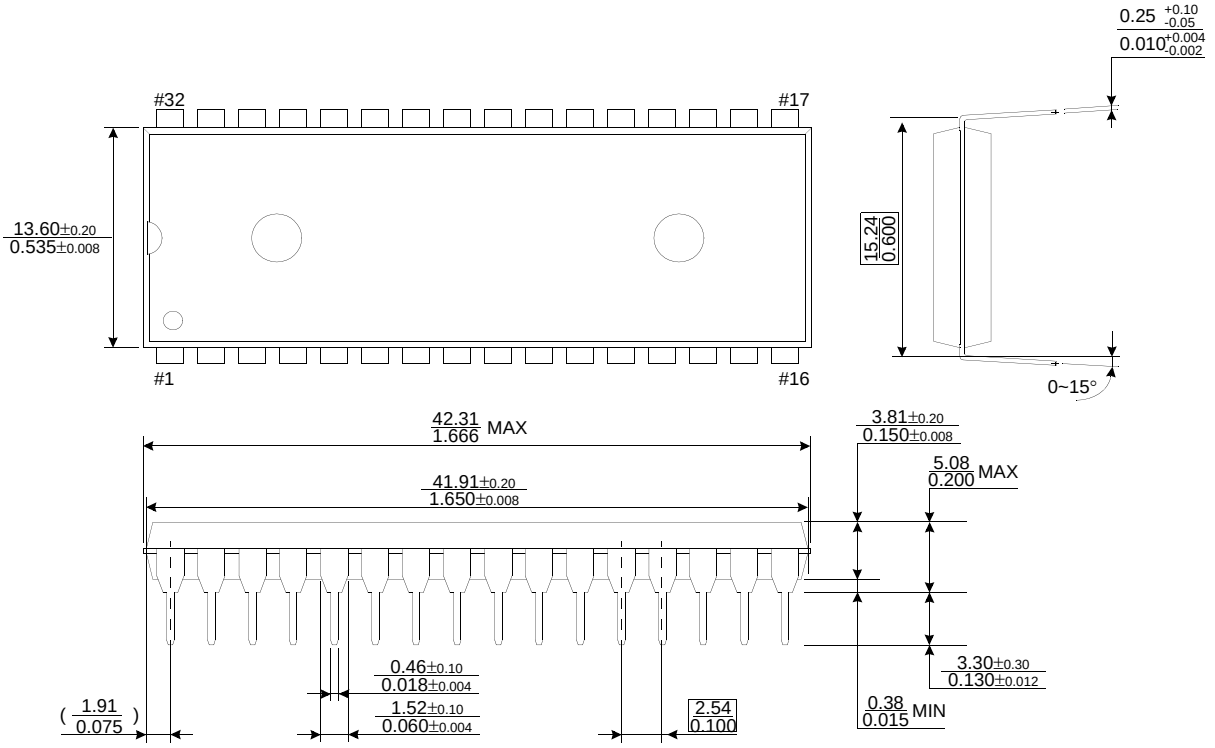
CS_2 controlled



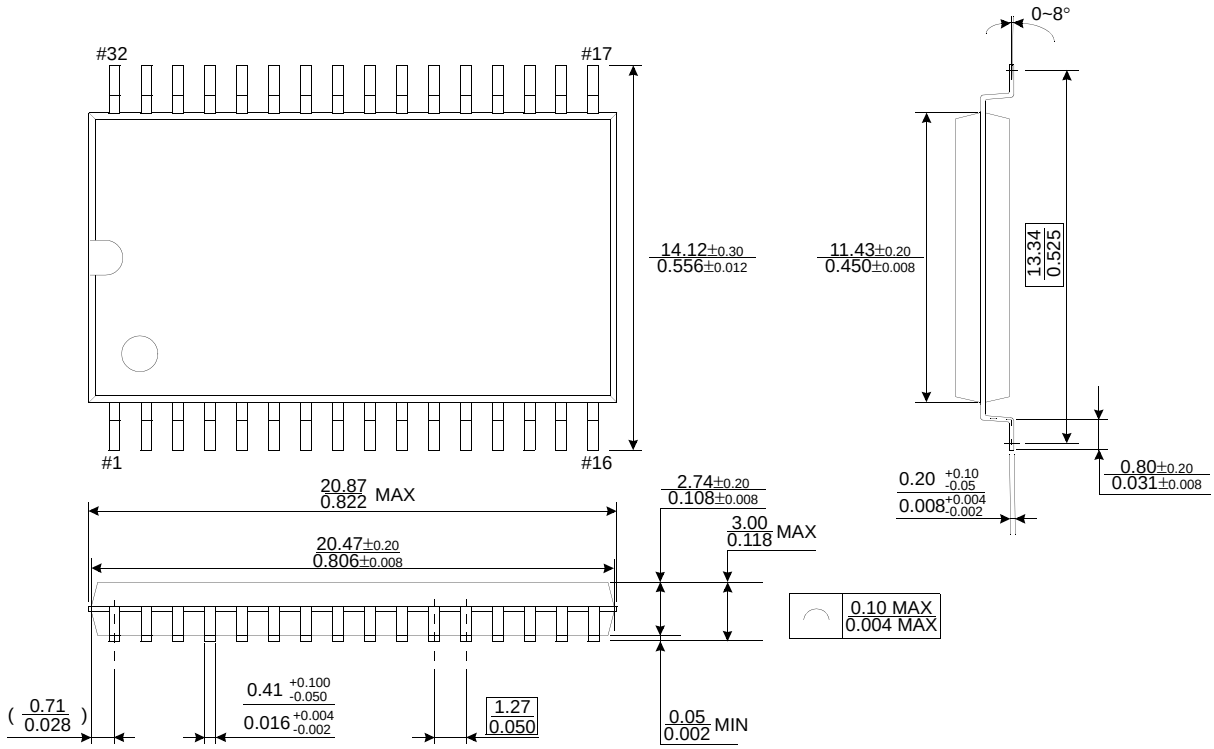
PACKAGE DIMENSIONS

Units: millimeters(inches)

32 DUAL INLINE PACKAGE (600mil)



32 PLASTIC SMALL OUTLINE PACKAGE (525mil)



PACKAGE DIMENSIONS

Units: millimeters(inches)

32 PIN THIN SMALL OUTLINE PACKAGE TYPE I (0820F)